



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20240628011.1**

**Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet,  
and additional Assembly site/BOM options for select devices  
Change Notification / Sample Request**

**Date:** June 28, 2024

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team  
SC Business Services

**20240628011.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS2041BDBVR	NULL
TPS2041BDGNR	NULL
TPS2041BDR	NULL
TPS2042BDGNR	NULL
TPS2042BDR	NULL
TPS2051BDGNR	NULL
TPS2051BDR	NULL
TPS2052BDGNR	NULL
TPS2061DBVR	NULL
TPS2061DGNR	NULL
TPS2061DR	NULL
TPS2062ADR	NULL
TPS2062DGNR	NULL
TPS2062DR	NULL
TPS2065DGNR	NULL
TPS2065DR	NULL
TPS2066DGNR	NULL
TPS2066DR	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20240628011.1	<b>PCN Date:</b>	June 28, 2024																		
<b>Title:</b>	Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet, and additional Assembly site/BOM options for select devices																				
<b>Customer Contact:</b>	Change Management Team	<b>Dept:</b>	Quality Services																		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	September 26, 2024	<b>Sample requests accepted until:</b>	July 28, 2024*																		
<b>*Sample requests received after July 28, 2024 will not be supported.</b>																					
<b>Change Type:</b>																					
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material																			
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process																			
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/> Wafer Fab Site																			
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/> Wafer Fab Material																			
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Wafer Fab Process																			
<b>PCN Details</b>																					
<b>Description of Change:</b>																					
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to Assembly site/BOM options for the devices listed below.																					
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>DL-LIN</td> <td>LBC4</td> <td>200 mm</td> <td>RFAB</td> <td>LBC9</td> <td>300 mm</td> </tr> </tbody> </table>			Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	DL-LIN	LBC4	200 mm	RFAB	LBC9	300 mm	
Current Fab Site			Additional Fab Site																		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																
DL-LIN	LBC4	200 mm	RFAB	LBC9	300 mm																
The die was also changed as a result of the process change.																					
Construction differences are as follows:																					
<b>Group 1 device</b>																					
	<b>FMX</b>	<b>MLA</b>																			
Wire type/Diam	1.98mil Cu	1.31mil Cu																			
<b>Group 2 device</b>																					
	<b>ASESH</b>	<b>UTL2</b>	<b>MLA</b>																		
Wire type/Diam	2.0mil Au	2.0mil Cu	1.31mil Cu																		
Mount compound	EY1000063	PZ0031	4224264																		
Mold compound	EN2000515	CZ0094	4211880																		
<b>Group 3 device</b>																					
	<b>TFME</b>	<b>UTL2</b>	<b>CDAT</b>																		
Wire type/Diam	1.30mil Au	1.30mil Au	1.31mil Cu																		
Mount compound	A-03	PZ0013	4207123																		
Mold compound	R-13	CZ0096	4222198																		
Qual details are provided in the Qual Data Section.																					
The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.																					

<b>Changes from Revision N (July 2023) to Revision O (June 2024)</b>	<b>Page</b>
• Updated origination date from June 2010 to April 2004 to match initial release of the data sheet.....	1
• Deleted Dissipation Ratings table.....	1
• Deleted "TPS2042xx and TPS2053xx" in table title.....	6
• Updated max UVLO and Supply current, high-level output values for the TPS2041BDR, TPS2041BDGNR, TPS2042BDR, TPS2042BDGNR, TPS2051BDR, TPS2051BDGNR, TPS2052BDGNR, and TPS2041BDBVR.....	7
• Updated Overcurrent trip threshold to apply only to TPS2042B and TPS2052B (DRB packages only).....	7
• .....	13
• Added TPS2051BDB.....	21
• Updated <a href="#">Section 8.3.7</a> to show that the TPS20x1B and TPS20x2B devices in the D, DGN, and DBV packages do not have overcurrent trip thresholds.....	21
• Updated <a href="#">Section 8.3.7.1</a> .....	22
• Updated <a href="#">Section 8.3.7.2</a> .....	22

<b>Changes from Revision J (August 2023) to Revision K (June 2024)</b>	<b>Page</b>
• Removed Dissipation Ratings table.....	1
• Added <a href="#">Section 6.3</a> .....	6
• Updated TPS2061, TPS2062, TPS2065, TPS2066 electrical characteristics, including overcurrent trip threshold, high-level output supply current and undervoltage lockout.....	6
• Updated TPS2061, TPS2062, TPS2065, TPS2066 Typical Characteristics.....	8
• Updated TPS2061, TPS2062, TPS2065, TPS2066 overcurrent description.....	19
• Updated <a href="#">Section 8.7.1</a> .....	19
• Updated <a href="#">Section 8.7.2</a> .....	20

<b>Changes from Revision A (March 2009) to Revision B (June 2024)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Deleted Dissipation Ratings table.....	1
• Thermal Information of new needle respin, TPS2066DGNR-1.....	4
• Added Thermal Information table.....	4
• Updated max UVLO value for TPS2066-1.....	4
• Updated max Supply current, high-level output for TPS2066-1.....	4
• Updated Overcurrent trip threshold to apply only to TPS2062-1 and TPS2065-1.....	4
• Updated section information.....	15
• Added <a href="#">Section 7.7.1</a> .....	16
• Added <a href="#">Section 7.7.2</a> .....	16

<b>Changes from Revision F (November 2008) to Revision G (June 2024)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Deleted Dissipation Ratings table.....	1
• Updated <a href="#">Table 4-1</a> footnote about PowerPad .....	3
• Added <a href="#">Section 5.3</a> .....	4
• Updated max UVLO for TPS2062A.....	4
• Updated max Supply current, high-level output values for TPS2062A.....	4
• Updated Overcurrent trip threshold to apply only to TPS2062ADRB, TPS2066ADRB, and TPS2066AD.....	4
• Updated <a href="#">Section 7.3</a> .....	13
• Added <a href="#">Section 7.3.1</a> .....	13
• Added <a href="#">Section 7.3.2</a> .....	13

<b>Product Folder</b>	<b>Current</b>	<b>New</b>	<b><a href="#">Link to full datasheet</a></b>
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	Datasheet Number	Datasheet Number	
TPS20xxB	SLVS514N	<b>SLVS514O</b>	<a href="http://www.ti.com/product/TPS2041B">http://www.ti.com/product/TPS2041B</a>
TPS206x	SLVS490J	<b>SLVS490K</b>	<a href="http://www.ti.com/product/TPS2061">http://www.ti.com/product/TPS2061</a>
TPS206x-1	SLVS714A	<b>SLVS714B</b>	<a href="http://www.ti.com/product/TPS2062-1">http://www.ti.com/product/TPS2062-1</a>
TPS206xA	SLVS798F	<b>SLVS798G</b>	<a href="http://www.ti.com/product/TPS2062A">http://www.ti.com/product/TPS2062A</a>

**Reason for Change:**

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Impact on Environmental Ratings:**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

**Changes to product identification resulting from this PCN:**

**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>


**Die Rev:**


Current	New
Die Rev [2P]	<b>Die Rev [2P]</b>
A, B	<b>A</b>

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TFME	NFM	CHN	Economic Development Zone
UTL2	NS2	THA	Bangpakong, Chachoengsao
FMX	MEX	MEX	Aguascalientes
ASESH	ASH	CHN	Shanghai
<b>MLA</b>	<b>MLA</b>	<b>MYS</b>	<b>Kuala Lumpur</b>
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label)


**TEXAS INSTRUMENTS**  
MADE IN: Malaysia  
2DC: 20:  
MSL '2 /260C/1 YEAR SEAL DT  
MSL 1 /235C/UNLIM 03/29/04  
OPT:  
ITEM: 39  
**LBL: 5A (L)T0:1750**



(1P) **SN74LS07NSR**  
(Q) **2000** (D) **0336**  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CS0: SHE (21L) CCO:USA  
(22L) AS0: MLA (23L) ACO: MYS

<b>Group 1 Product Affected:</b>			
TPS2041BDR	TPS2051BDR	TPS2062ADR	TPS2065DR
TPS2042BDR	TPS2061DR	TPS2062DR	TPS2066DR
<b>Group 2 Product Affected:</b>			
TPS2041BDGNR	TPS2052BDGNR	TPS2065DGNR	
TPS2042BDGNR	TPS2061DGNR	TPS2066DGNR	
TPS2051BDGNR	TPS2062DGNR	TPS2066DGNR-1	
<b>Group 3 Product Affected:</b>			
TPS2041BDBVR	TPS2061DBVR		

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS2041BDR	Qual Device: TPS2041BDGNR	Qual Device: TPS2042BDR	Qual Device: TPS2042BDGNR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1	QBS Reference: TPS2051BDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	1/77/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/231/0	-	3/135/0	-
HTSL	A6	High Temperature Storage Life	175C	420 Hours	-	-	-	-	-	1/77/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	3/2400/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	1/76/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: TPS2041BDR	Qual Device: TPS2041BDGMR	Qual Device: TPS2042BDR	Qual Device: TPS2042BDGMR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1	QBS Reference: TPS2051BDR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	-	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	1/3/0	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	1/6/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	1/30/0	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	1/30/0	-	3/90/0	-

- QBS: Qual By Similarity
- Qual Device TPS2041BDR is qualified at MSL1 260C
- Qual Device TPS2041BDGMR is qualified at MSL1 260C
- Qual Device TPS2042BDR is qualified at MSL1 260C
- Qual Device TPS2042BDGMR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2304-069

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS2061DGMR	Qual Device: TPS2061DR	Qual Device: TPS2062DGMR	Qual Device: TPS2062DR	Qual Device: TPS2062ADR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	1/77/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	-	3/135/0
HTSL	A6	High Temperature Storage Life	175C	420 Hours	-	-	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	-	3/2400/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	-	1/76/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	-	1/15/0



Type	#	Test Name	Condition	Duration	Qual Device: TPS2061DGNR	Qual Device: TPS2061DR	Qual Device: TPS2062DGNR	Qual Device: TPS2062DR	Qual Device: TPS2062ADR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	3/30/0	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	1/3/0	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0	-	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	1/30/0	-	3/90/0

- QBS: Qual By Similarity
- Qual Device TPS2061DGNR is qualified at MSL1 260C
- Qual Device TPS2061DR is qualified at MSL1 260C
- Qual Device TPS2062DGNR is qualified at MSL1 260C
- Qual Device TPS2062DR is qualified at MSL1 260C
- Qual Device TPS2062ADR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2304-071

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS2065DGNR	Qual Device: TPS2065DR	Qual Device: TPS2066DGNR	Qual Device: TPS2066DR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/231/0	-	3/135/0
HTSL	A6	High Temperature Storage Life	175C	420 Hours	-	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	3/2400/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	1/76/0	-



Type	#	Test Name	Condition	Duration	Qual Device: TPS2065DGNR	Qual Device: TPS2065DR	Qual Device: TPS2066DGNR	Qual Device: TPS2066DR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	-	-	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	-	-	-	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30	-	-	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	1/30/0	-	3/90/0

- QBS: Qual By Similarity
- Qual Device TPS2065DGNR is qualified at MSL1 260C
- Qual Device TPS2065DR is qualified at MSL1 260C
- Qual Device TPS2066DGNR is qualified at MSL1 260C
- Qual Device TPS2066DR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2304-073

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS2051BDR	Qual Device: TPS2051BDGNR	QBS Reference: UCC27624QDGNRQ1	QBS Reference: TPS2052BDR	QBS Reference: LMV393QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-	3/135/0
HTSL	A6	High Temperature Storage Life	175C	420 Hours	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	1/76/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TPS2051BDR</a>	Qual Device: <a href="#">TPS2051BDGMR</a>	QBS Reference: <a href="#">UCC27624QDGNRQ1</a>	QBS Reference: <a href="#">TPS2052BDR</a>	QBS Reference: <a href="#">LMV393QDRQ1</a>
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	1/30/0	-	3/90/0

- QBS: Qual By Similarity
- Qual Device TPS2051BDR is qualified at MSL1 260C
- Qual Device TPS2051BDGMR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2304-070

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TPS2066DGNR-1</a>	Qual Device: <a href="#">TPS2052BDGMR</a>	QBS Package Reference: <a href="#">UCC27624QDGNRQ1</a>	QBS Process/Product Reference: <a href="#">TPS2052BDR</a>	QBS Process Reference: <a href="#">LMV393QDRQ1</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/6/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TPS2066DGNR-1</a>	Qual Device: <a href="#">TPS2052BDGNR</a>	QBS Package Reference: <a href="#">UCC27624QDGNRQ1</a>	QBS Process/Product Reference: <a href="#">TPS2052BDR</a>	QBS Process Reference: <a href="#">LMV393QDRQ1</a>
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0	-

- QBS: Qual By Similarity
- Qual Device TPS2066DGNR-1 is qualified at MSL1 260C
- Qual Device TPS2052BDGNR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

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TI Qualification ID: R-CHG-2304-090

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TPS2065DBVR</a>	Qual Device: <a href="#">TPS2065DBVR</a>	QBS Package/Process Reference: <a href="#">TPS25221DBVR</a>	QBS Package Reference: <a href="#">TLV9061DBVR</a>	QBS Package/Process/Product Reference: <a href="#">TPS2051BDBVR</a>	QBS Package Reference: <a href="#">TLV62568DBVR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	3/231/0	-	-
HTOL	B1	Life Test	140C	480 Hours	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	3/9/0	3/228/0	1/76/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/9/0	3/228/0	1/76/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TPS2065DBVR</a>	Qual Device: <a href="#">TPS2065DBVR</a>	QBS Package/Process Reference: <a href="#">TPS25221DBVR</a>	QBS Package Reference: <a href="#">TLV9061DBVR</a>	QBS Package/Process/Product Reference: <a href="#">TPS2051BDBVR</a>	QBS Package Reference: <a href="#">TLV62568DBVR</a>
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	3/66/0	-	1/22/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	1/5/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	4000 Volts	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	-
FTY	E6	Final Test Yield	-	-	1/PASS	1/PASS	-	-	-	-

- QBS: Qual By Similarity
- Qual Device TPS2065DBVR is qualified at MSL1 260C
- Qual Device TPS2065DBVR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

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TI Qualification ID: R-CHG-2208-005

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